

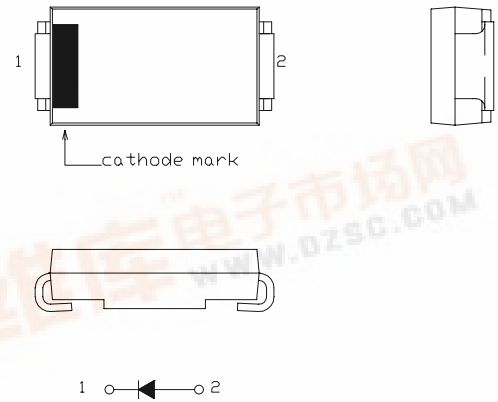


OUTLINE DRAWING

FRD Type : NSF03A20

FEATURES

- \* **FLAT-PAK** Surface Mount Device
- \* Ultra F<sub>sat</sub> Recovery
- \* High Surge Capability
- \* Low Forward Voltage Drop
- \* Low Power Loss, High Efficiency
- \* Packaged in 16mm Tape and Reel
- \* Not Rolling During Assembly



Maximum Ratings

Approx Net Weight:016g

Rating	Symbol	NSF03A20		Unit
Repetitive Peak Reverse Voltage	$V_{RRM}$	200		V
Average Rectified Output Current	$I_O$	1.61	Ta=25 °C *1	50Hz Half Sine Wave Resistive Load
		3.0	Tl=106 °C *2	
RMS Forward Current	$I_{F(RMS)}$	4.71		A
Surge Forward Current	$I_{FSM}$	45	50Hz Half Sine Wave, 1cycle Non-repetitive	A
Operating Junction Temperature Range	$T_{jw}$	-40 to +150		°C
Storage Temperature Range	$T_{stg}$	-40 to +150		°C

Electrical • Thermal Characteristics

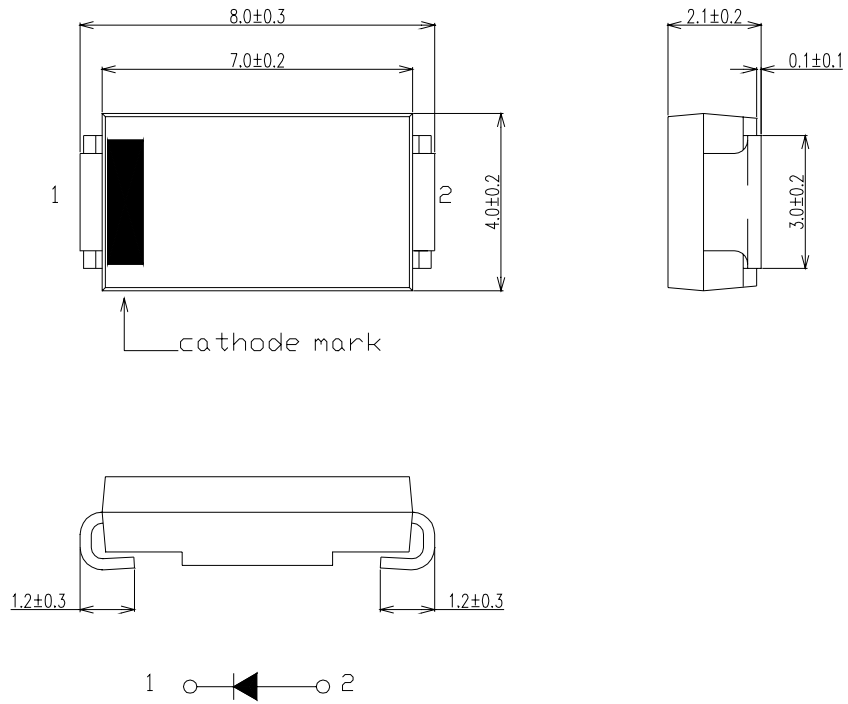
Characteristics	Symbol	Conditions	Min.	Typ.	Max.	Unit
Peak Reverse Current	$I_{RM}$	Tj= 25°C, $V_{RM}= V_{RRM}$	-	-	10	μA
Peak Forward Voltage	$V_{FM}$	Tj= 25°C, $I_{FM}= 3.0A$	-	-	0.98	V
Reverse Recovery Time	trr	Ta= 25°C, $I_{FM}=3.0 A$ -di/dt=50A/μs			30	ns
Thermal Resistance	$R_{th(j-a)}$	Junction to Ambient *1	-	-	89	°C /W
	$R_{th(j-l)}$	Junction to Lead	-	-	13	

\*1 Alumina Substrate Mounted (Soldering Lands=2x3.5mm,Both Sides)

\*2 Tl= Lead Temperature



NSF03A20 OUTLINE DRAWING (Dimensions in mm)



SOLDERING PAD

